

**RELIABILITY MONITOR REPORT
FOR**

DAL B8 Process

Dallas Semiconductor

**4401 South Beltwood Parkway
Dallas, TX 75244-3292**

**This Report was prepared by
Dallas Semiconductor Reliability Engineering**

Summary:

The data in the tables that follow was generated as the result of an on-going Process Reliability Monitor. The specific products in this process monitor are:

DS2413	DS8007
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The calculated failure rate for devices using this process is:

FAILURE RATE: **MTTF (YRS): 10575** **FITS: 10.8**

The parameters used to calculate this failure rate are as follows:

Cf: 60% **Ea: 0.7** **Tu: 25 °C**

The reliability data follows. At the start of this data is the process information. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available. This report covers data between 10/1/2006 and 9/30/2007 .

Device Information:

Process: DAL B8 Process
Interconnect: Aluminum / 1% Silicon / 0.5% Copper
Gate Oxide Thickness: 175 Å

OPERATING LIFE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
HIGH TEMP OP LIFE	0713	DS2413	125C, 5.25 VOLTS	1000 HRS	45	0	
HIGH TEMP OP LIFE	0724	DS8007	125C, 6.0 VOLTS	1000 HRS	45	0	
				Total:		0	

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